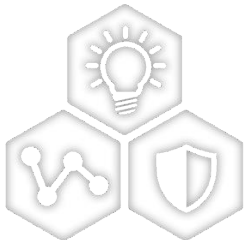


**CCB 7907**  
**Pre and Post Change Summary**  
**PCN #: CENO-01UVKE616**



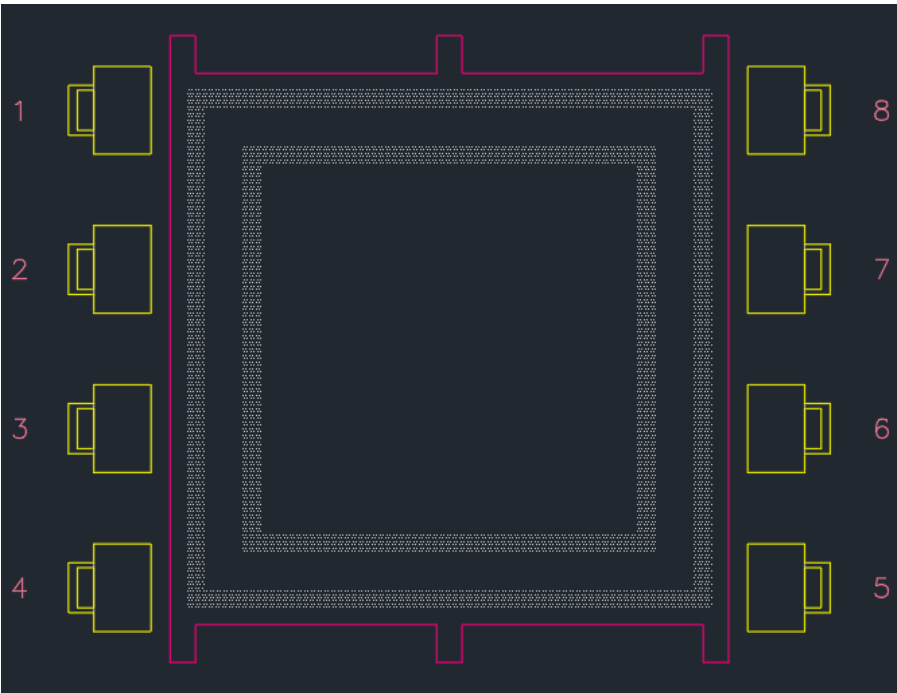
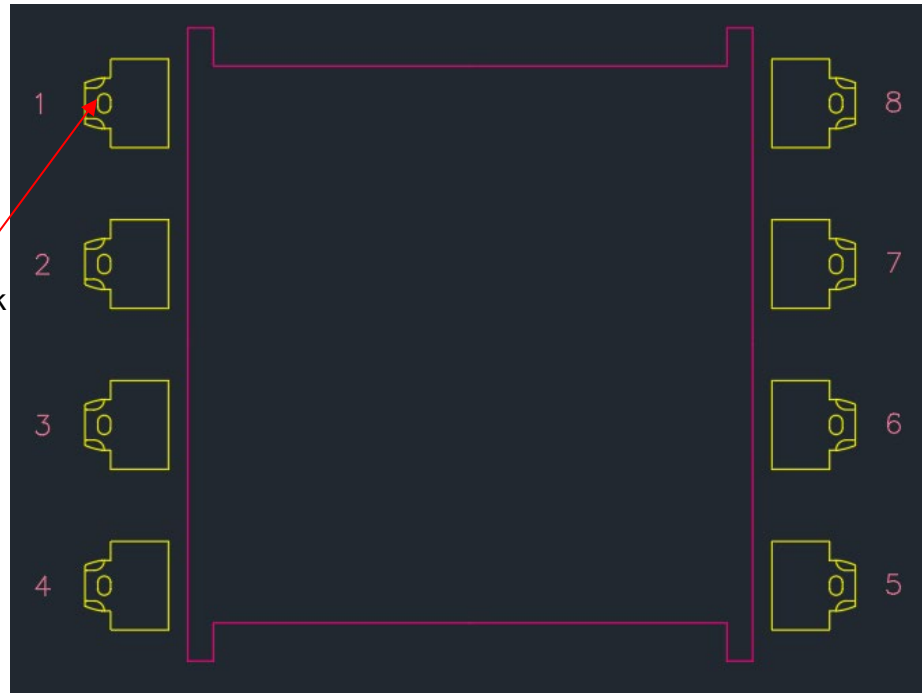
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# Lead Frame Comparison

NSEB		MMT	
			
<b>Lead-Frame Material</b>	EFTEC-64T	<b>Lead-Frame Material</b>	A194
<b>Lead-Lock</b>	Yes (Dimple)	<b>Lead-Lock</b>	Yes (Locking Hole)
<b>DAP Surface Prep</b>	Ag ring	<b>DAP Surface Prep</b>	Bare Cu

Note 1: Not to scale

Note 2: Mold compound materials fills the leadlock hole, which provides improved protection against moisture penetration along the edge of the leads (pins) of the package.